



High power cycling capability
Low on-state and switching losses
Designed for traction and industrial applications

Phase Control Thyristor Type T393-2500-52

Maximum allowable mean on-state current		I _{TAV}		2500 A	
Repetitive peak off-state voltage		V _{DRM}		4600...5200 V	
Repetitive peak reverse voltage		V _{RRM}			
Turn-off time		t _q		800 μs	
V _{DRM} , V _{RRM} , V	4600	4800	5000	5200	
Voltage code	46	48	50	52	
T _j , °C	-60...+125				

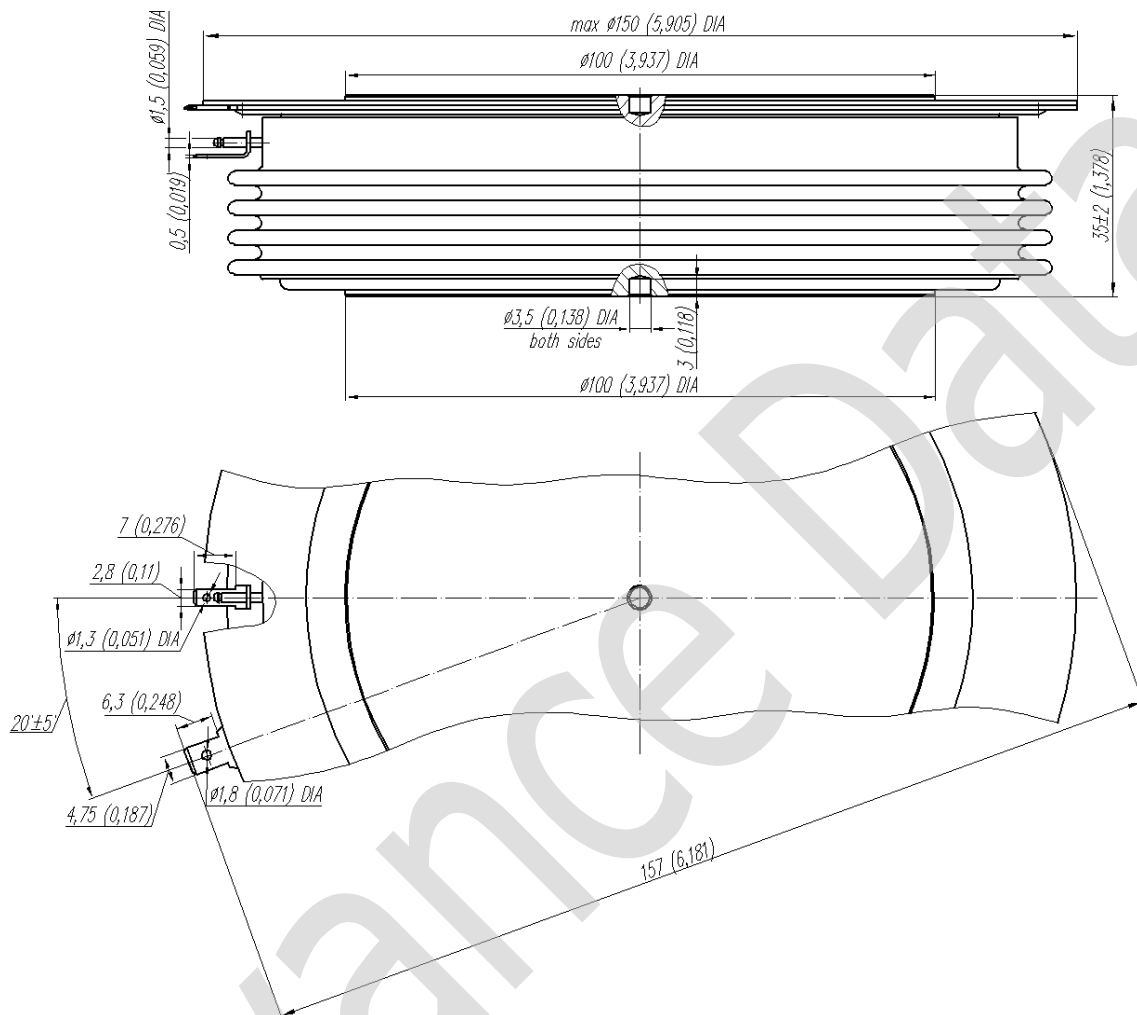
MAXIMUM ALLOWABLE RATINGS

Symbols and parameters		Units	Values	Test conditions	
ON-STATE					
I_{TAV}	Maximum allowable mean on-state current	A	2500 3600	$T_c=94\text{ }^{\circ}\text{C}$, Double side cooled $T_c=70\text{ }^{\circ}\text{C}$, Double side cooled 180° half-sine wave; 50 Hz	
I_{TRMS}	RMS on-state current	A	3925	$T_c=94\text{ }^{\circ}\text{C}$, Double side cooled 180° half-sine wave; 50 Hz	
I_{TSM}	Surge on-state current	kA	55.0 63.0	$T_j=T_{j\text{ max}}$ $T_j=25\text{ }^{\circ}\text{C}$	180° half-sine wave; $t_p=10\text{ ms}$; single pulse; $V_D=V_R=0\text{ V}$; Gate pulse: $I_G=2\text{ A}$; $t_{GP}=50\text{ }\mu\text{s}$; $di_G/dt\geq 1\text{ A}/\mu\text{s}$
			58.0 67.0	$T_j=T_{j\text{ max}}$ $T_j=25\text{ }^{\circ}\text{C}$	180° half-sine wave; $t_p=8.3\text{ ms}$; single pulse; $V_D=V_R=0\text{ V}$; Gate pulse: $I_G=2\text{ A}$; $t_{GP}=50\text{ }\mu\text{s}$; $di_G/dt\geq 1\text{ A}/\mu\text{s}$
I^2t	Safety factor	$A^2s\cdot 10^3$	15100 19800	$T_j=T_{j\text{ max}}$ $T_j=25\text{ }^{\circ}\text{C}$	180° half-sine wave; $t_p=10\text{ ms}$; single pulse; $V_D=V_R=0\text{ V}$; Gate pulse: $I_G=2\text{ A}$; $t_{GP}=50\text{ }\mu\text{s}$; $di_G/dt\geq 1\text{ A}/\mu\text{s}$
			13900 18600	$T_j=T_{j\text{ max}}$ $T_j=25\text{ }^{\circ}\text{C}$	180° half-sine wave; $t_p=8.3\text{ ms}$; single pulse; $V_D=V_R=0\text{ V}$; Gate pulse: $I_G=2\text{ A}$; $t_{GP}=50\text{ }\mu\text{s}$; $di_G/dt\geq 1\text{ A}/\mu\text{s}$
BLOCKING					
V_{DRM}, V_{RRM}	Repetitive peak off-state and Repetitive peak reverse voltages	V	4600...5200	$T_{j\text{ min}}<T_j<T_{j\text{ max}}$; 180° half-sine wave; 50 Hz; Gate open	
V_{DSM}, V_{RSM}	Non-repetitive peak off-state and Non-repetitive peak reverse voltages	V	4700...5300	$T_{j\text{ min}}<T_j<T_{j\text{ max}}$; 180° half-sine wave; single pulse; Gate open	
V_D, V_R	Direct off-state and Direct reverse voltages	V	$0.6\cdot V_{DRM}$ $0.6\cdot V_{RRM}$	$T_j=T_{j\text{ max}}$; Gate open	

TRIGGERING					
I_FGM	Peak forward gate current	A	12	T _j =T _{j max}	
V_RGM	Peak reverse gate voltage	V	5		
P_G	Gate power dissipation	W	5	T _j =T _{j max} for DC gate current	
SWITCHING					
(di _T /dt) _{crit}	Critical rate of rise of on-state current non-repetitive (f=1 Hz)	A/μs	1000	T _j =T _{j max} ; V _D =0.67·V _{DRM} ; I _{TM} =2 I _{TAV} ; Gate pulse: I _G =2 A; t _{GP} =50 μs; di _G /dt≥2 A/μs	
THERMAL					
T _{stg}	Storage temperature	°C	−60...+50		
T _j	Operating junction temperature	°C	−60...+125		
MECHANICAL					
F	Mounting force	kN	70.0...90.0		
a	Acceleration	m/s ²	50	Device clamped	

CHARACTERISTICS

Symbols and parameters		Units	Values	Conditions	
ON-STATE					
V _{TM}	Peak on-state voltage, max	V	2.10	T _j =25 °C; I _{TM} =6300 A	
V _{T(TO)}	On-state threshold voltage, max	V	1.00	T _j =T _{j max} ;	
r _T	On-state slope resistance, max	mΩ	0.190	0.5 π I _{TAV} < I _T < 1.5 π I _{TAV}	
I _L	Latching current, max	mA	1500	T _j =25 °C; V _D =12 V; Gate pulse: I _G =2 A; t _{GP} =50 μs; di _G /dt≥1 A/μs	
I _H	Holding current, max	mA	300	T _j =25 °C; V _D =12 V; Gate open	
BLOCKING					
I _{DRM} , I _{RRM}	Repetitive peak off-state and Repetitive peak reverse currents, max	mA	300	T _j =T _{j max} ; V _D =V _{DRM} ; V _R =V _{RRM}	
(dv _D /dt) _{crit}	Critical rate of rise of off-state voltage ¹⁾ , min	V/μs	500, 1000, 1600	T _j =T _{j max} ; V _D =0.67·V _{DRM} ; Gate open	
TRIGGERING					
V _{GT}	Gate trigger direct voltage, max	V	5.00 3.00 2.00	T _j = T _{j min} T _j =25 °C T _j = T _{j max}	V _D =12 V; I _D =3 A; Direct gate current
I _{GT}	Gate trigger direct current, max	mA	500 300 200	T _j = T _{j min} T _j = 25 °C T _j = T _{j max}	
V _{GD}	Gate non-trigger direct voltage, min	V	0.35	T _j =T _{j max} ; V _D =0.67·V _{DRM} ; Direct gate current	
I _{GD}	Gate non-trigger direct current, min	mA	15.00		
SWITCHING					
t _{gd}	Delay time	μs	4.00	T _j =25 °C; V _D =1500 V; I _{TM} =I _{TAV} ; di/dt=200 A/μs; Gate pulse: I _G =2 A; V _G =20 V; t _{GP} =50 μs; di _G /dt=2 A/μs	
t _q	Turn-off time ²⁾ , max	μs	800	dv _D /dt=50 V/μs; T _j =T _{j max} ; I _{TM} =1000 A; di _R /dt=-5 A/μs; V _R =100 V; V _D =1600 V;	
Q _{rr}	Recovered charge, max	μC	12500	T _j =T _{j max} ; I _{TM} =1000 A;	
t _{rr}	Reverse recovery time, max	μs	157	di _R /dt=-5 A/μs;	
I _{rr}	Reverse recovery current, max	A	159	V _R =100 V	



All dimensions in millimeters (inches)

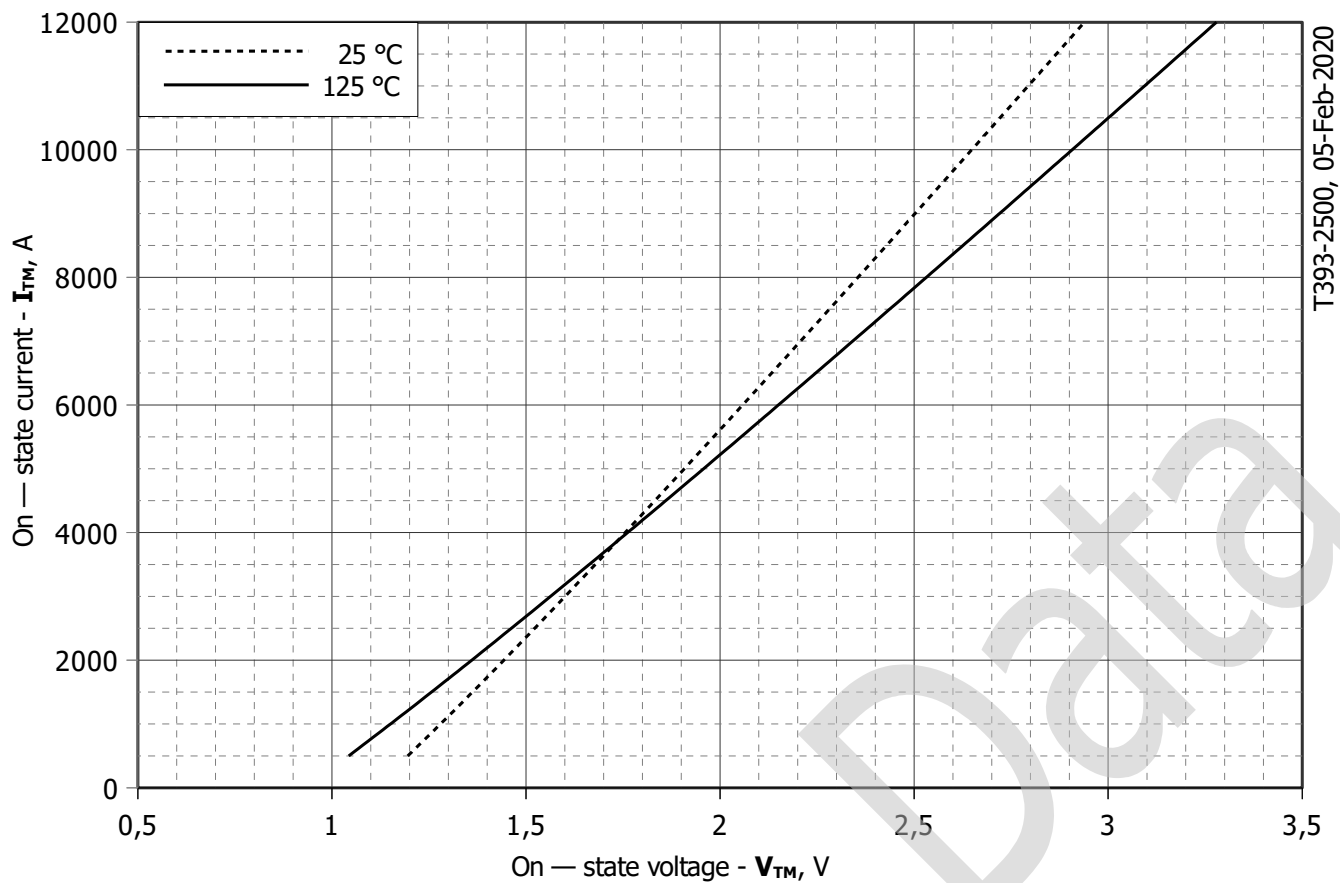


Fig 1 – On-state characteristics of Limit device

Analytical function for On-state characteristic:

$$V_T = A + B \cdot i_T + C \cdot \ln(i_T + 1) + D \cdot \sqrt{i_T}$$

	Coefficients for max curves	
	$T_j = 25^\circ\text{C}$	$T_j = T_{j\max}$
A	1.17300000	1.04510000
B	0.00012979	0.00016438
C	-0.01979700	-0.03193100
D	0.00360030	0.00512580

On-state characteristic model (see Fig. 1)

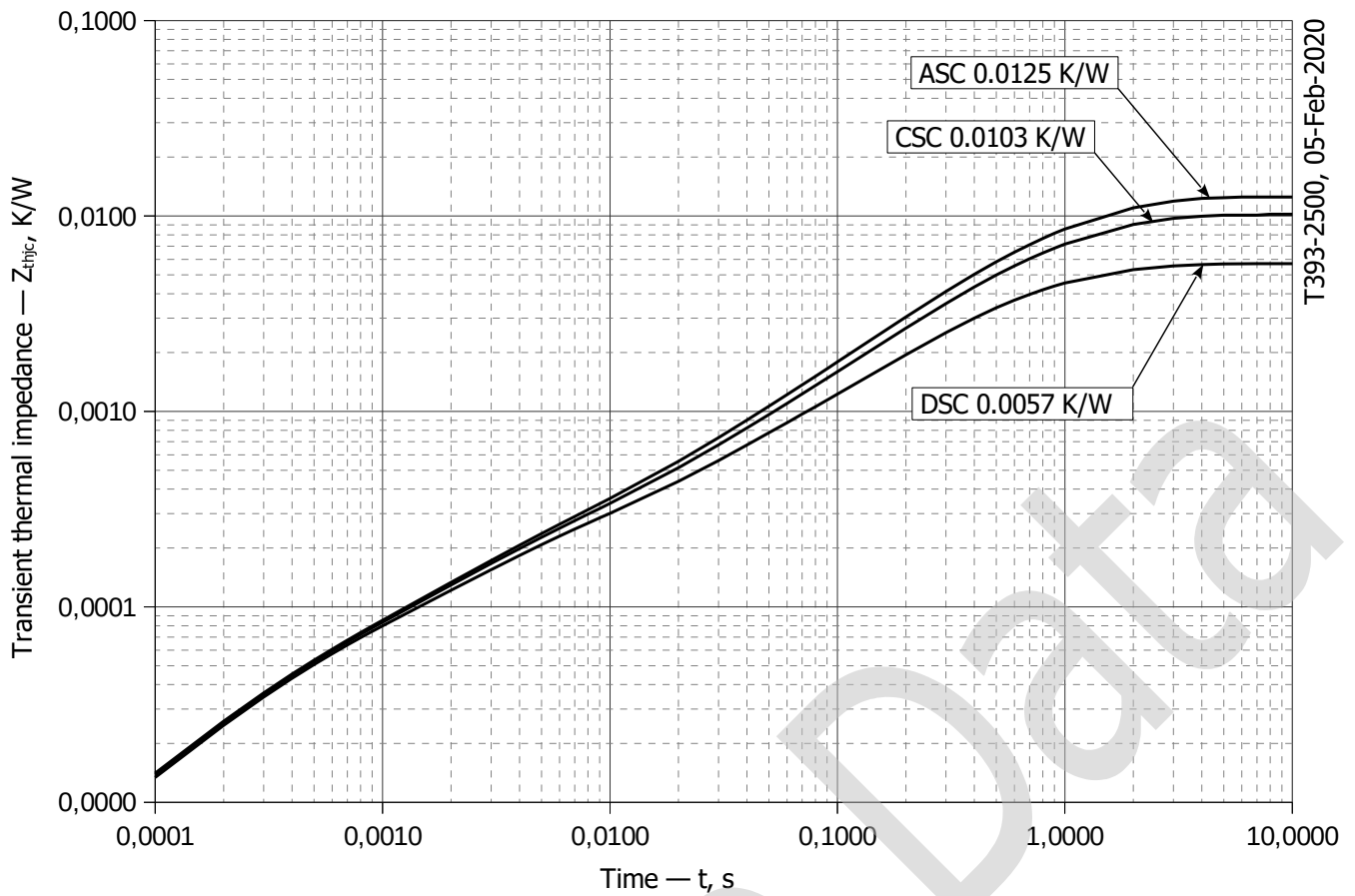


Fig 2 – Transient thermal impedance Z_{thjc} vs. time t

Analytical function for Transient thermal impedance junction to case Z_{thjc} for DC:

$$Z_{thjc} = \sum_{i=1}^n R_i \left(1 - e^{-\frac{t}{\tau_i}} \right)$$

Where $i = 1$ to n , n is the number of terms in the series.

t = Duration of heating pulse in seconds.

Z_{thjc} = Thermal resistance at time t .

R_i = Amplitude of p_{th} term.

τ_i = Time constant of r_{th} term.

DC Double side cooled

i	1	2	3	4	5	6
R_i , K/W	0.002457	-0.003548	0.002909	0.0002069	3.51e-005	0.00364
τ_i , s	1.062	0.005022	0.3787	0.0257	0.0003732	0.004916

DC Anode side cooled

i	1	2	3	4	5	6
R_i , K/W	0.006812	0.002637	0.002729	0.0001806	0.000122	3.069e-005
τ_i , s	1.06	1.131	0.3835	0.02886	0.003033	0.0003349

DC Cathode side cooled

i	1	2	3	4	5	6
R_i , K/W	0.004458	0.002601	0.002763	0.0001806	0.0001224	3.094e-005
τ_i , s	1.06	1.100	0.3794	0.0291	0.003057	0.0003374

Transient thermal impedance junction to case Z_{thjc} model (see Fig. 2)

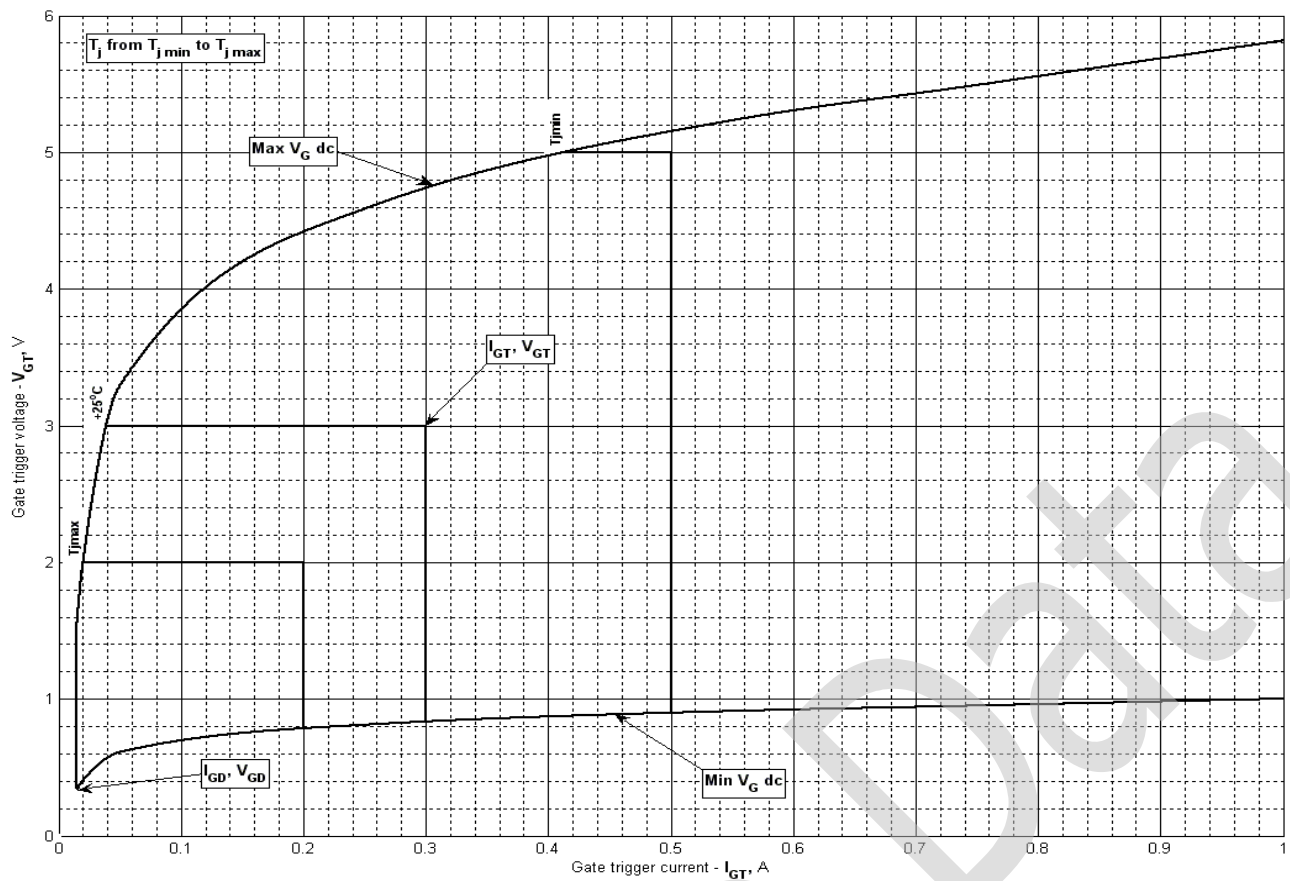


Fig 3 – Gate characteristics – Trigger limits

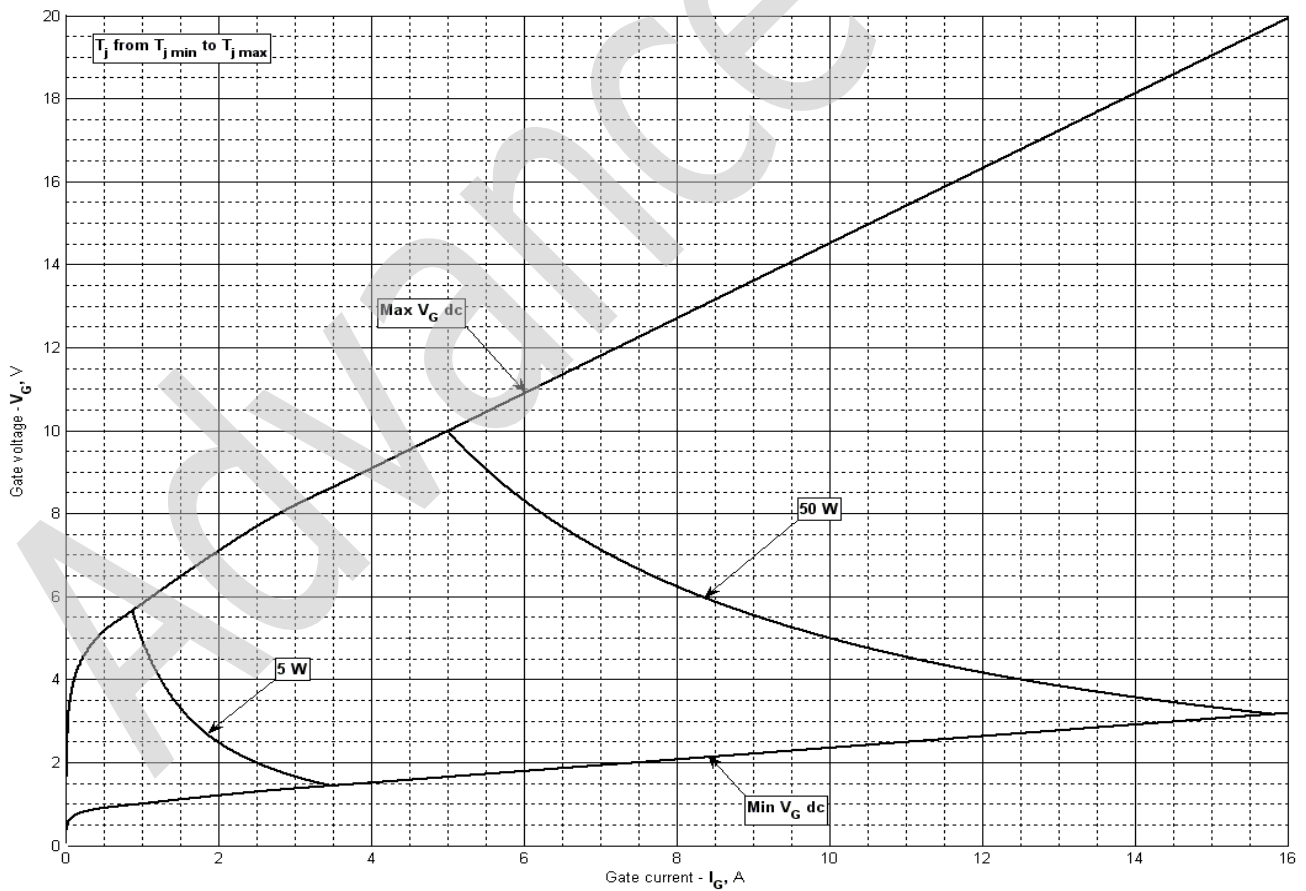


Fig 4 - Gate characteristics – Power curves

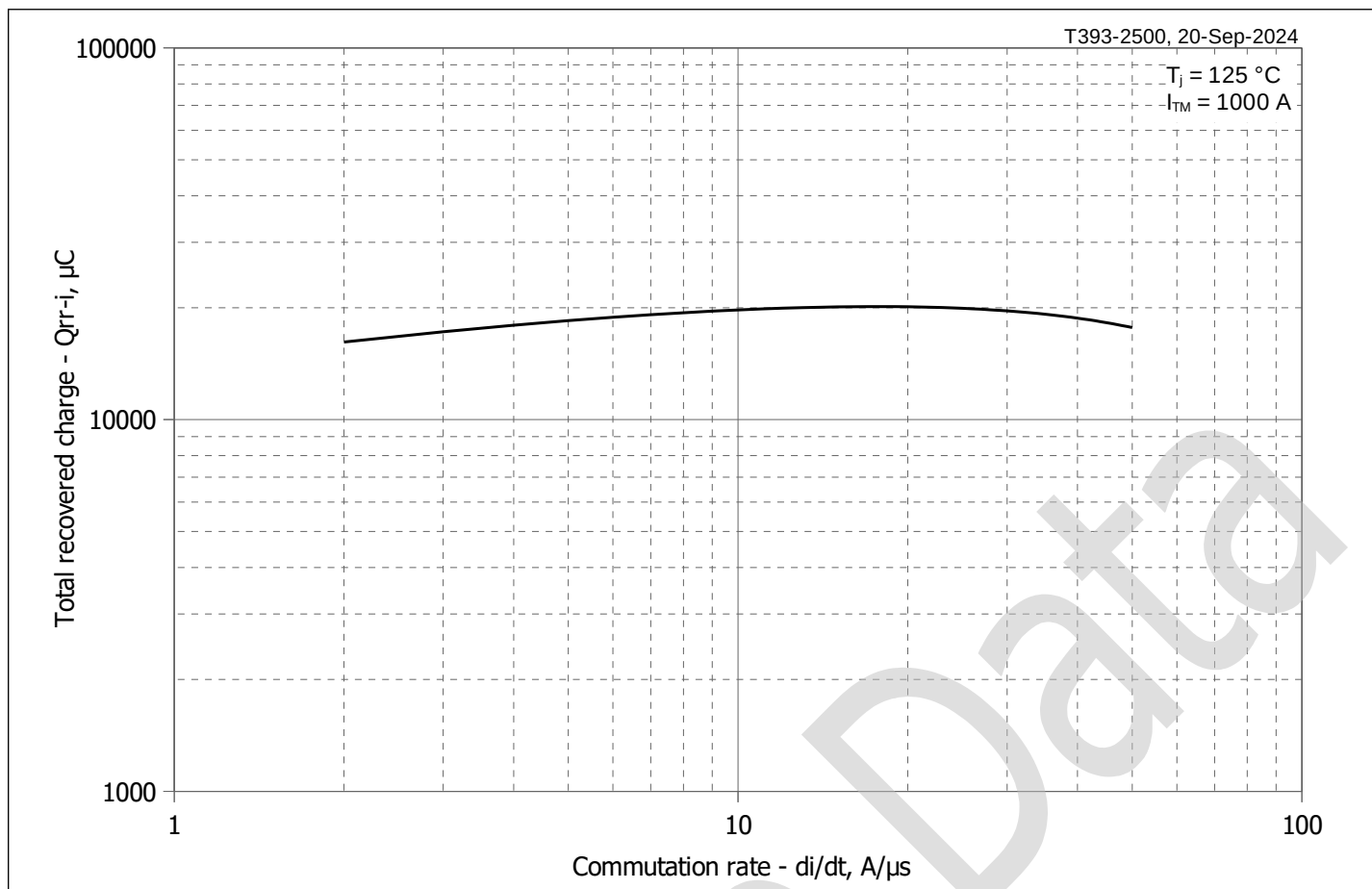


Fig 5 – Maximum recovered charge Q_{rr-i} (integral) vs. commutation rate di_R/dt

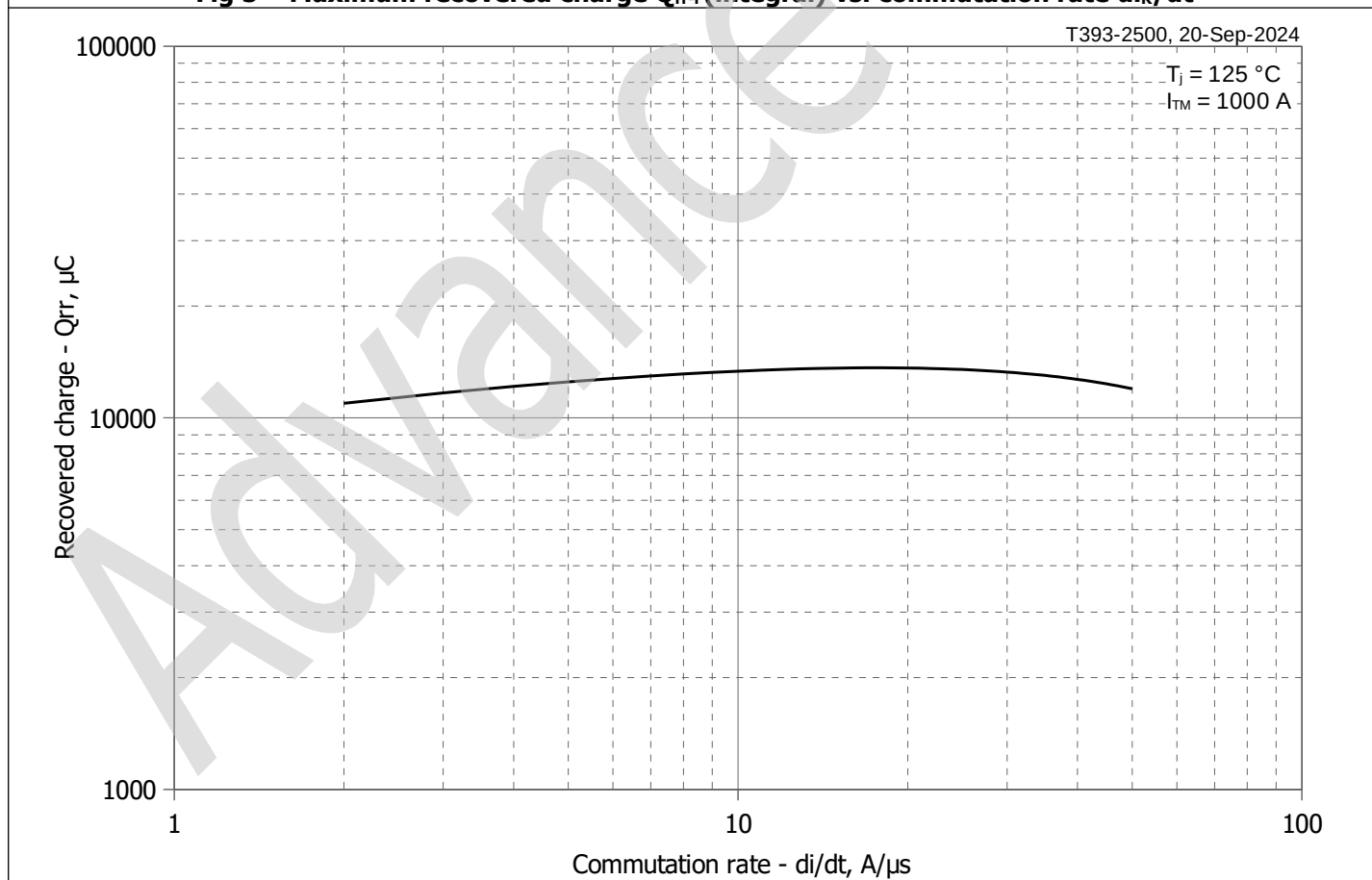


Fig 6 – Maximum recovered charge Q_{rr} vs. commutation rate di_R/dt (25% chord)

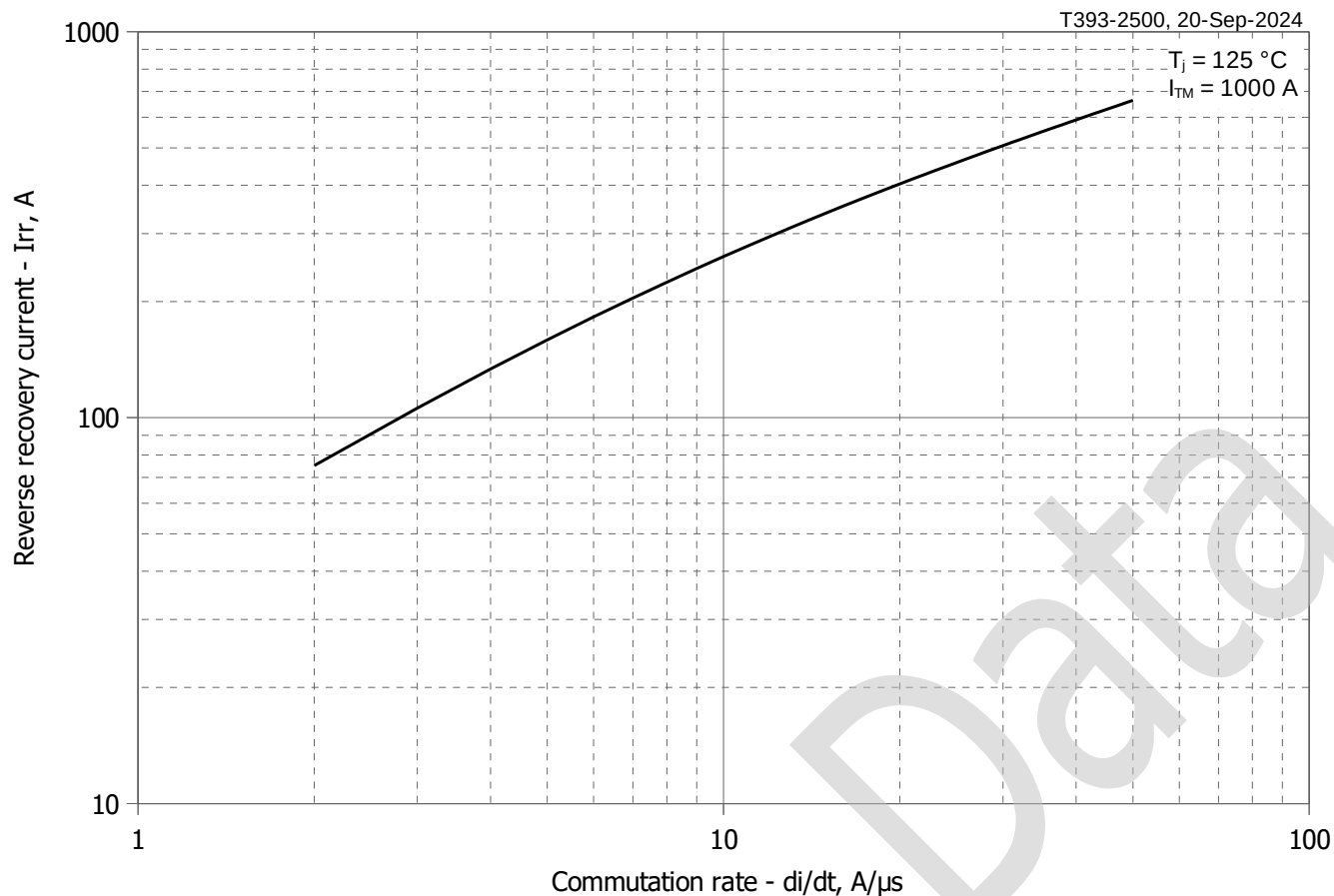


Fig 7 – Maximum reverse recovery current I_{rr} vs. commutation rate di_R/dt

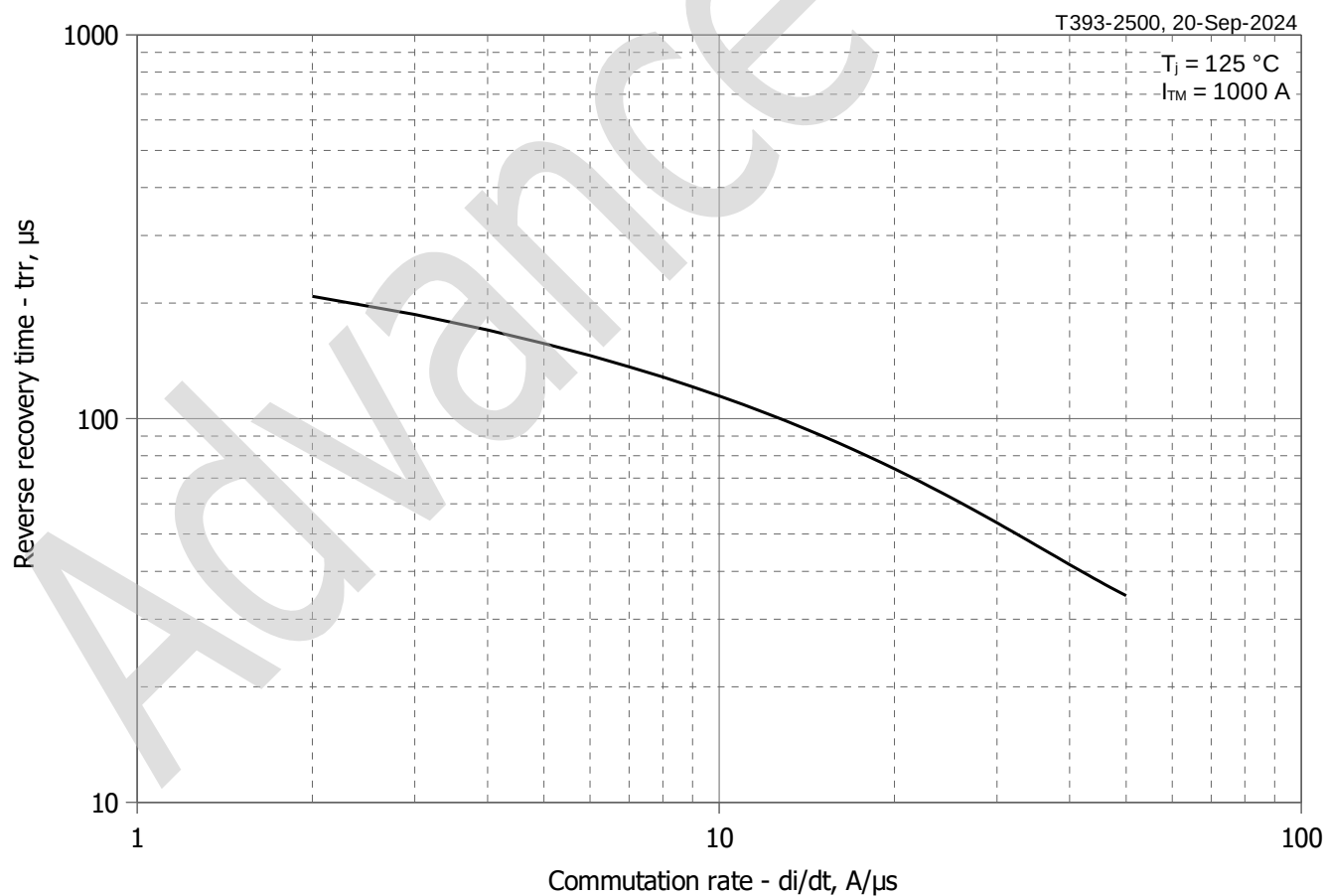
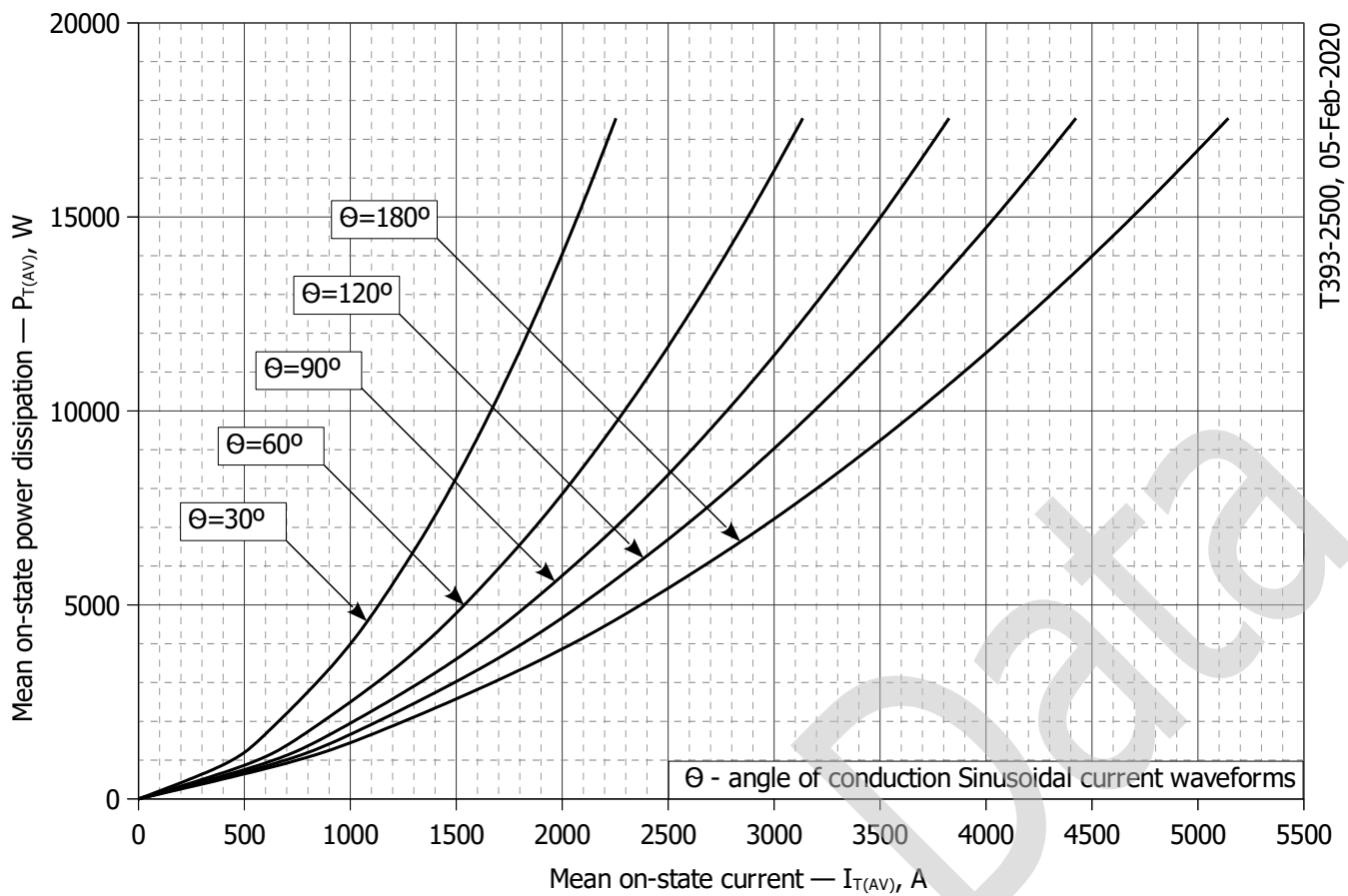
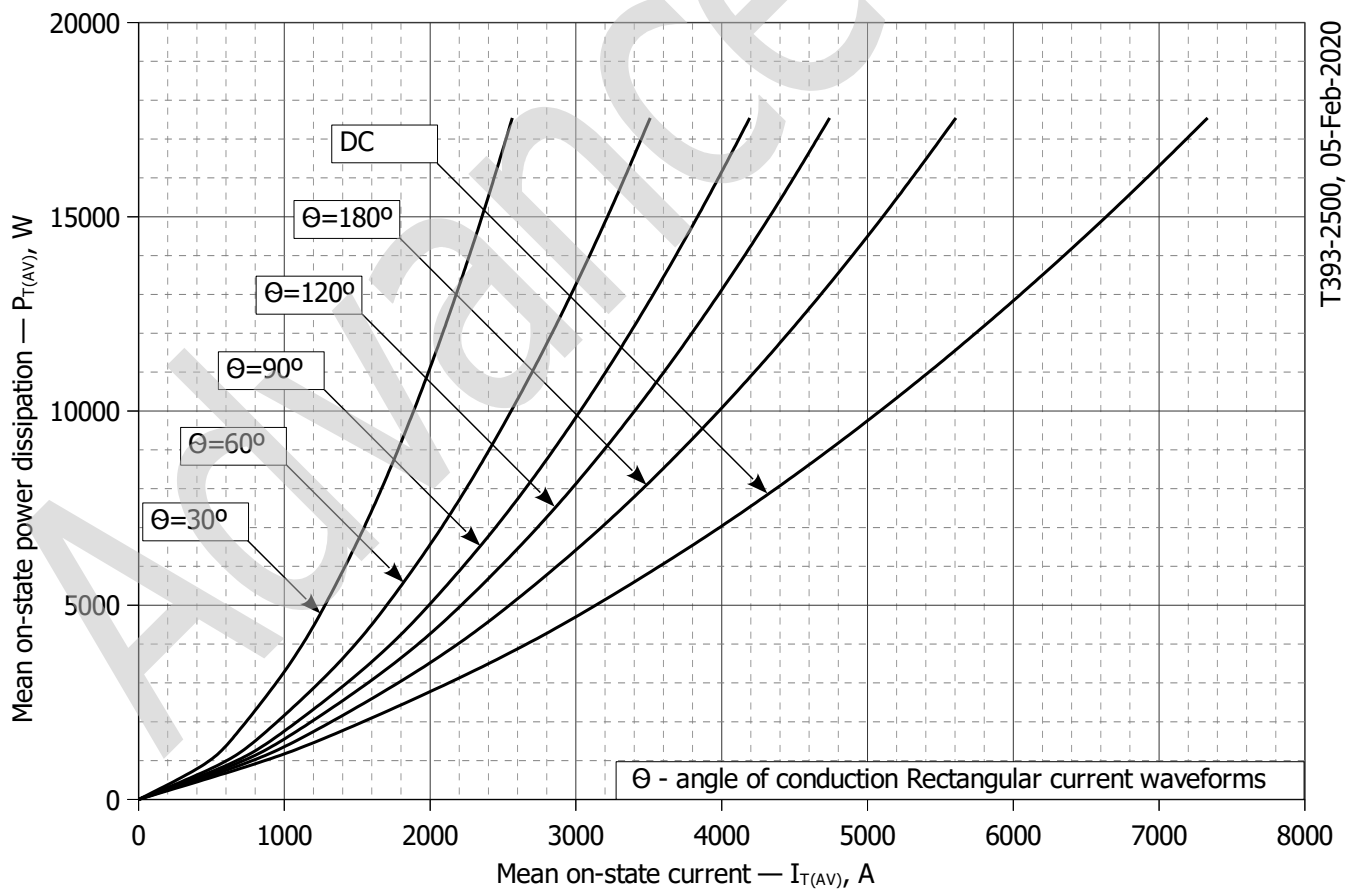


Fig 8 – Maximum recovery time t_r vs. commutation rate di_R/dt (25% chord)



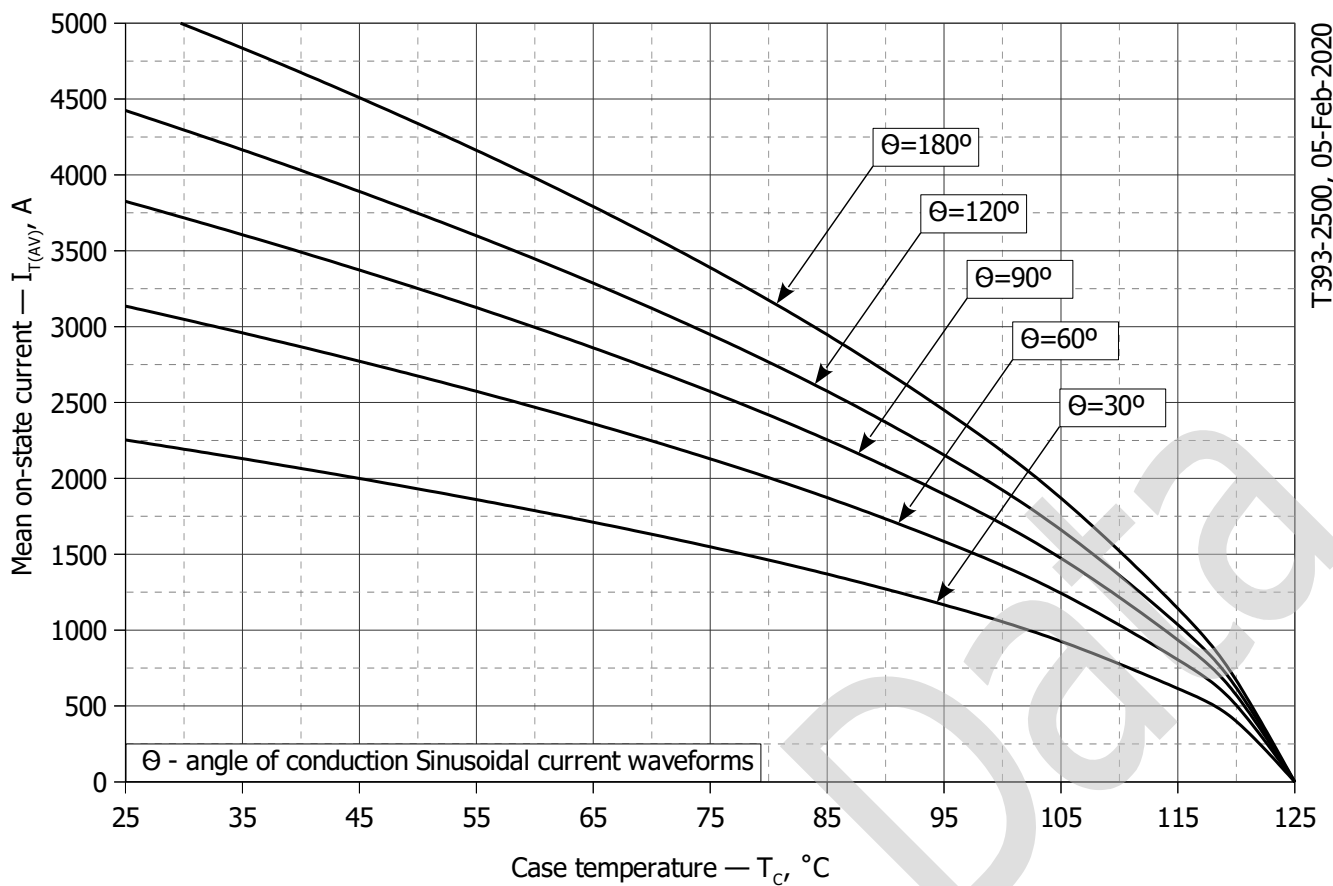
T393-2500, 05-Feb-2020

Fig. 9 - Mean on-state power dissipation P_{TAV} vs. mean on-state current I_{TAV} for sinusoidal current waveforms at different conduction angles ($f=50\text{Hz}$, DSC)



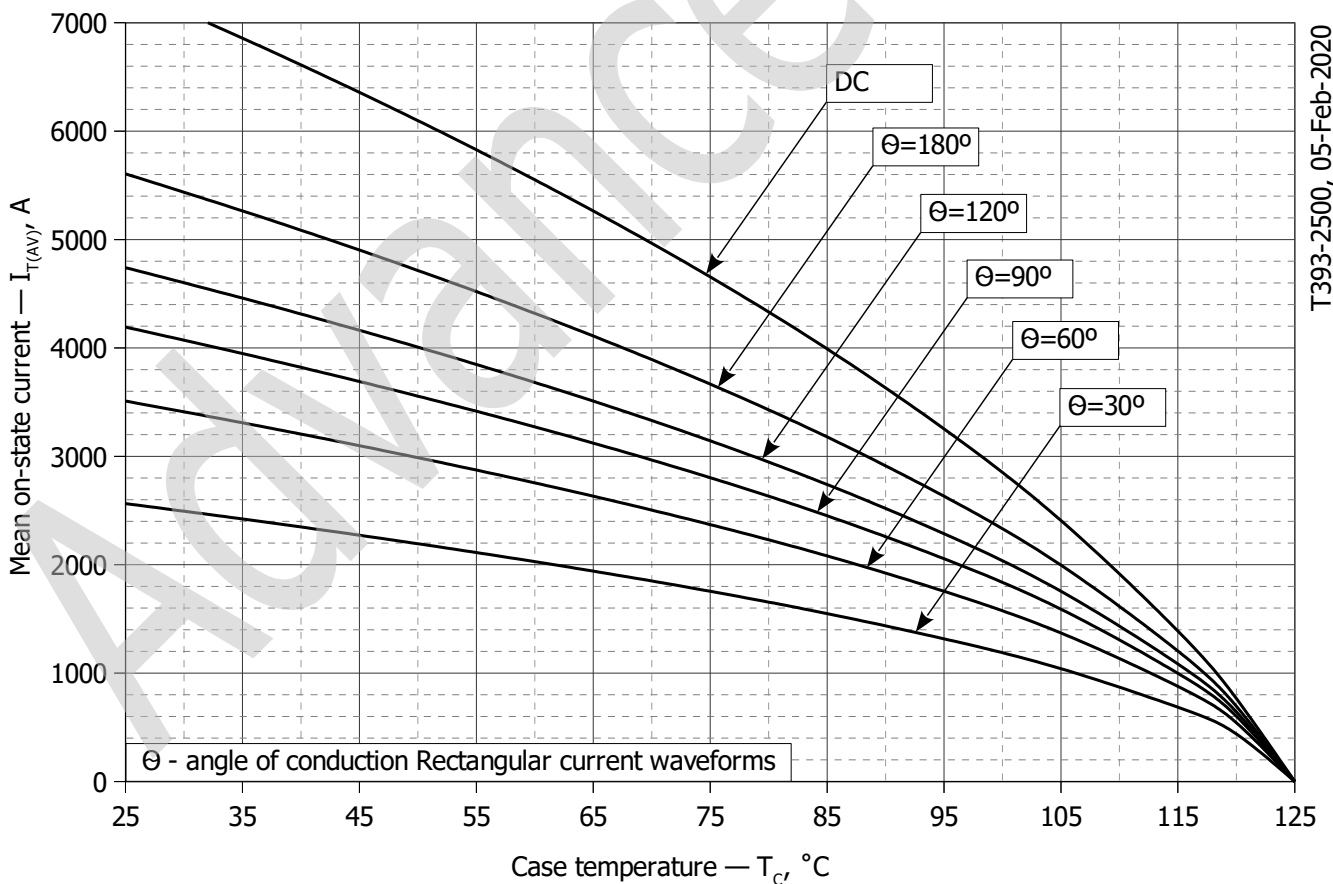
T393-2500, 05-Feb-2020

Fig. 10 – Mean on-state power dissipation P_{TAV} vs. mean on-state current I_{TAV} for rectangular current waveforms at different conduction angles and for DC ($f=50\text{Hz}$, DSC)



T393-2500, 05-Feb-2020

Fig. 11 – Mean on-state current I_{TAV} vs. case temperature T_c for sinusoidal current waveforms at different conduction angles ($f=50\text{Hz}$, DSC)



T393-2500, 05-Feb-2020

Fig. 12 - Mean on-state current I_{TAV} vs. case temperature T_c for rectangular current waveforms at different conduction angles and for DC ($f=50\text{Hz}$, DSC)

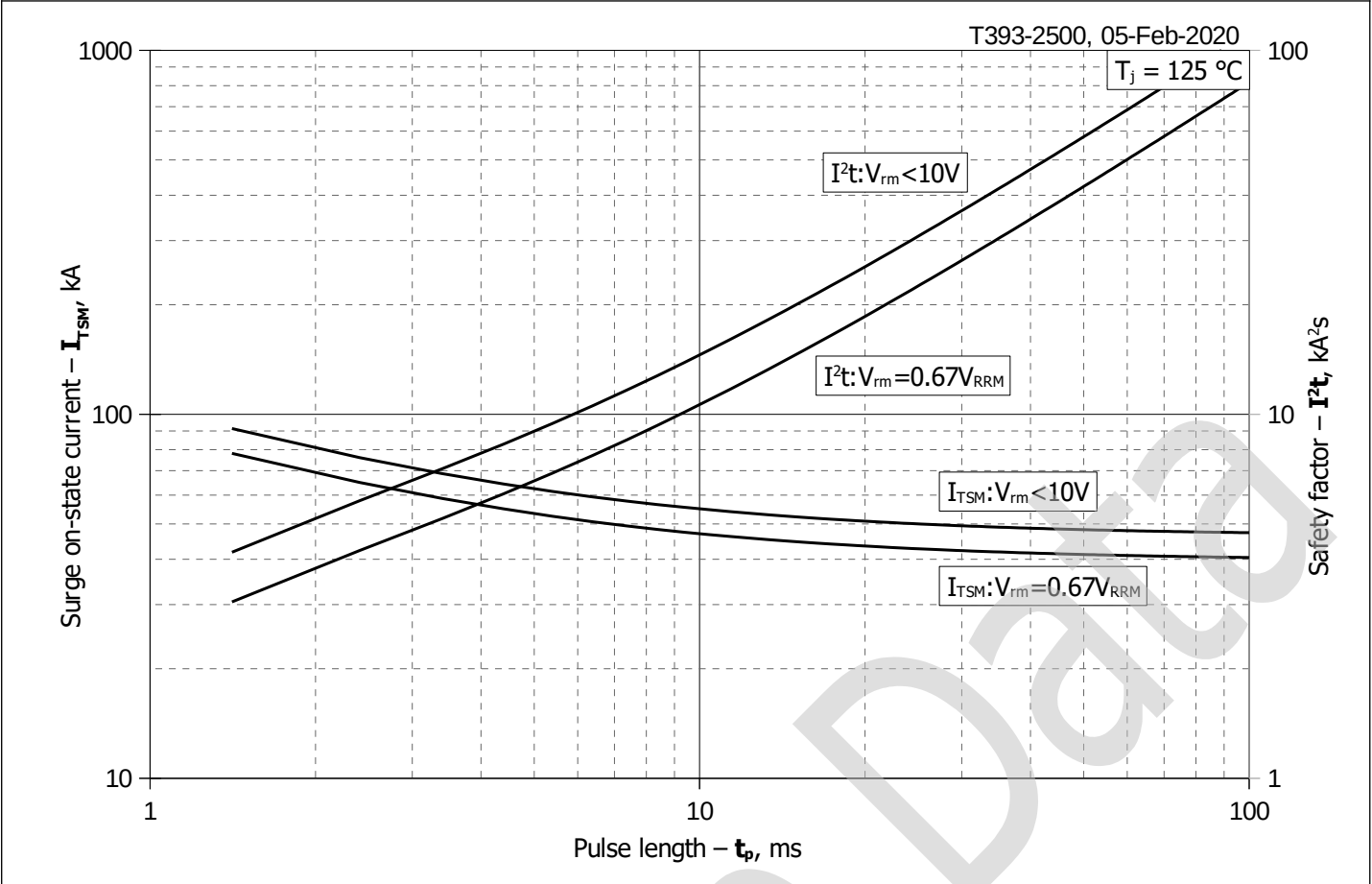


Fig. 13 – Maximum surge on-state current I_{TSM} and safety factor I^2t vs. pulse length t_p

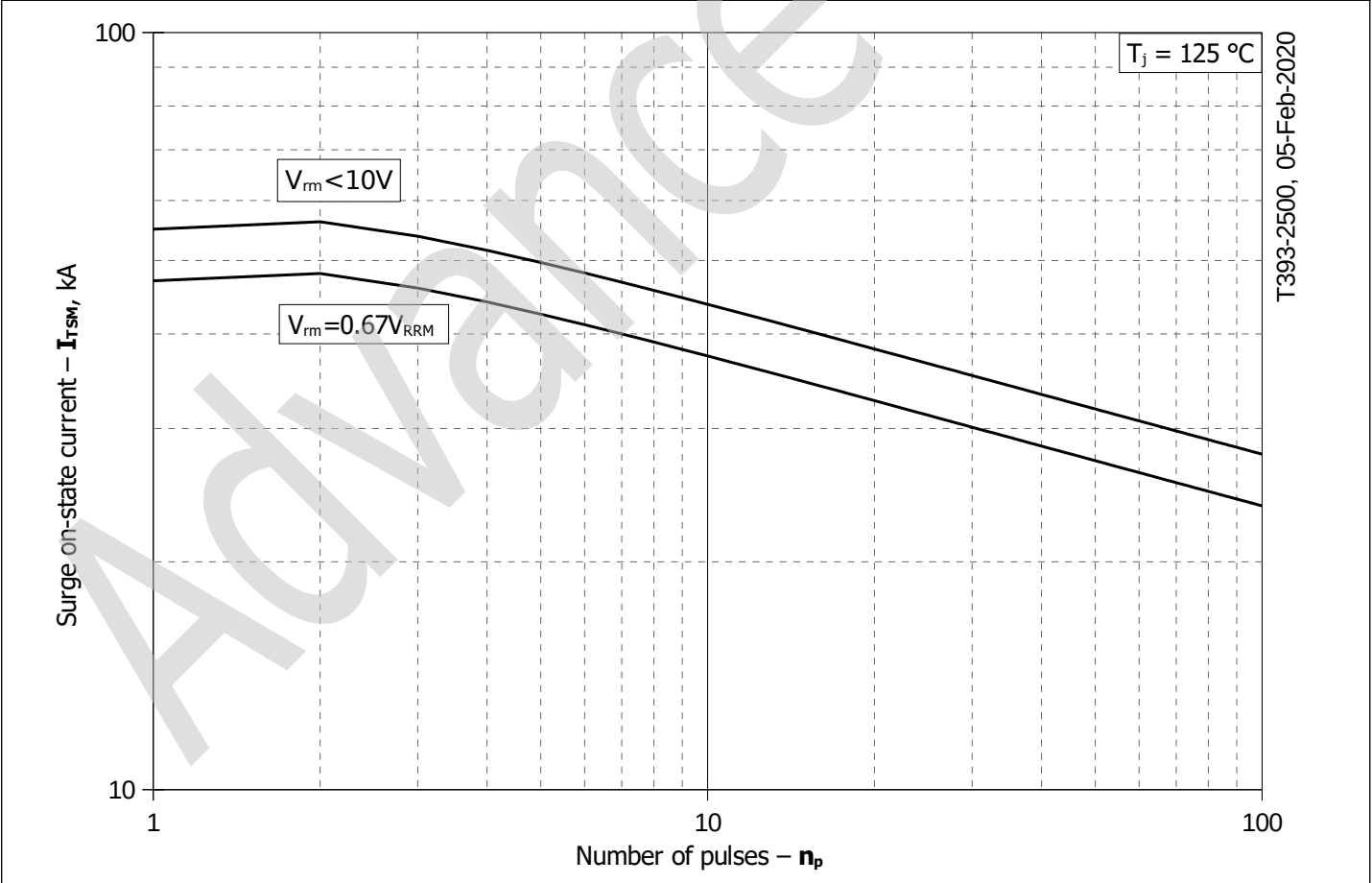


Fig. 14 - Maximum surge on-state current I_{TSM} vs. number of pulses n_p